

**1024-BIT BIPOLAR RAM (1024x1)****82S10/82S110 (Q.C.)****82S11/82S111 (T.S.)**

82S10/110-F,N • 82S11/111-F,N

**DESCRIPTION**

The 82S10/11, with a typical access time of 30ns, is ideal for cache buffer applications and for systems requiring very high speed main memory.

The 82S10/11 family requires single +5V power supply and features very low current pnp input structures. They include on-chip decoding and a chip enable input for ease of memory expansion, and feature either open collector or tri-state outputs for optimization of word expansion in bused organizations.

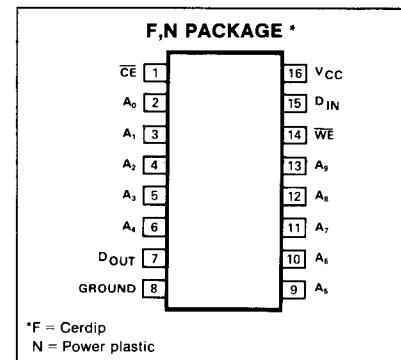
All devices are available in the commercial temperature range (0°C to +75°C) and are specified as N82S10/110/11/111. The 82S10 and 82S11 are also available in the military temperature range (-55°C to +125°C) and are specified as S82S10/11.

**FEATURES**

- Address access time:  
N82S10/11: 40ns max  
S82S10/11: 60ns max  
N82S110/111: 30ns max
- Write cycle time:  
N82S10/11: 40ns max  
S82S10/11: 60ns max  
N82S110/111: 30ns max
- Power dissipation: 0.5W/bit typ
- Input loading:  
N82S10/11: -250 $\mu$ A max  
S82S10/11: -250 $\mu$ A max  
N82S110/111: -250 $\mu$ A max
- Output options:  
82S10/110: Open collector  
82S11/111: Tri-state
- On-chip address decoding
- Non-inverting output
- Blanked output during Write
- Fully TTL compatible

**APPLICATIONS**

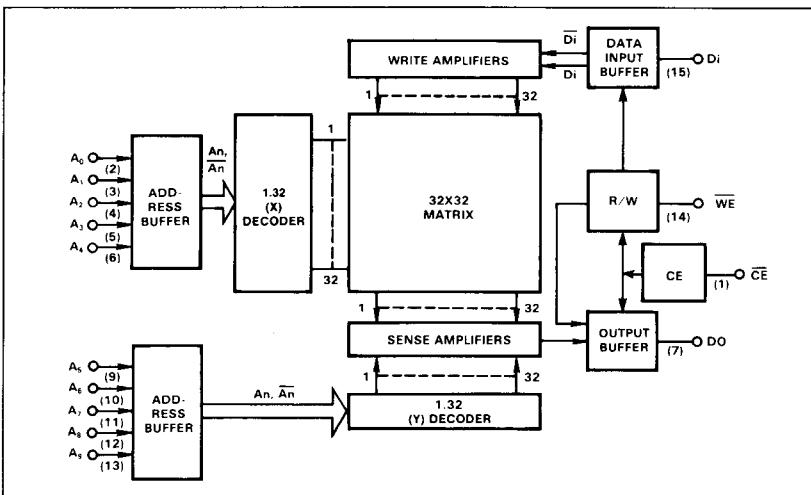
- High speed main frame
- Cache memory
- Buffer storage
- Writable control store

**PIN CONFIGURATION****TRUTH TABLE**

MODE	CE	WE	D	D <sub>OUT</sub>	
				82S10/110	82S11/111
Read	0	1	X	Stored data	Stored data
Write "0"	0	0	0	1	High-Z
Write "1"	0	0	1	1	High-Z
Disabled	1	X	X	1	High-Z

X = Don't care.

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**BLOCK DIAGRAM**

**1024-BIT BIPOLAR RAM (1024x1)****82S10/82S110 (0.C.)****82S11/82S111 (T.S.)**

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**BIPOLAR MEMORY****ABSOLUTE MAXIMUM RATINGS**

PARAMETER <sup>1</sup>	RATING	UNIT
V <sub>CC</sub>	Supply voltage	+7
V <sub>IN</sub>	Input voltage	+5.5
	Output voltage	Vdc
V <sub>OH</sub>	High (82S10/110)	+5.5
V <sub>O</sub>	Off-state (82S11/111)	Vdc
T <sub>A</sub>	Temperature range Operating N82S10/11/110/111 S82S10/11	+5.5 °C
T <sub>STG</sub>	Storage	-65 to +150

**DC ELECTRICAL CHARACTERISTICS<sup>2</sup>** N82S10/110/11/111: 0°C ≤ T<sub>A</sub> ≤ +75°C, 4.75V ≤ V<sub>CC</sub> ≤ 5.25VS82S10/11: -55°C ≤ T<sub>A</sub> ≤ +125°C, 4.5V ≤ V<sub>CC</sub> ≤ 5.5V

PARAMETER	TEST CONDITIONS	N82S10/11/110/111			S82S10/11			UNIT
		Min	Typ <sup>3</sup>	Max	Min	Typ <sup>3</sup>	Max	
V <sub>IL</sub> V <sub>IH</sub> V <sub>IC</sub>	Input voltage Low <sup>1</sup> High <sup>1</sup> Clamp <sup>1,4</sup>	V <sub>CC</sub> = Min V <sub>CC</sub> = Max V <sub>CC</sub> = Min, I <sub>IN</sub> = -12mA	2.1	.85 -1.0 -1.5	2.1	.80 -1.0 -1.5	V	
V <sub>OL</sub> V <sub>OH</sub>	Output voltage Low <sup>1,5</sup> High (82S11/111) <sup>1,6</sup>	V <sub>CC</sub> = Min I <sub>OL</sub> = 16mA I <sub>OH</sub> = -2mA	2.4	0.35 0.45	2.4	0.35 0.50	V	
I <sub>IL</sub> I <sub>IH</sub>	Input current Low High	V <sub>IN</sub> = 0.45V V <sub>IN</sub> = 5.5V		-10 1 -250 25		-10 1 -250 40	μA	
I <sub>OLK</sub> I <sub>O(OFF)</sub>	Output current Leakage (82S10/110) <sup>7</sup> Hi-Z state (82S11/111)	V <sub>CC</sub> = Max V <sub>OUT</sub> = 5.5V V <sub>OUT</sub> = 5.5V V <sub>OUT</sub> = 0.45V <sup>7</sup> V <sub>OUT</sub> = 0V		1 1 -1 -60 -100		1 1 -1 -100 -100	μA μA	
I <sub>OS</sub>	Short circuit (82S11/111) <sup>8</sup>	-20		-20			mA	
I <sub>CC</sub>	V <sub>CC</sub> supply current <sup>9</sup>	V <sub>CC</sub> = Max 0 < T <sub>A</sub> < 25°C T <sub>A</sub> ≥ 25°C T <sub>A</sub> ≤ 0°C		120 95 155 130 170		120 95 155 130 170	mA	
C <sub>IN</sub> C <sub>OUT</sub>	Capacitance Input Output	V <sub>CC</sub> = 5.0V V <sub>IN</sub> = 2.0V V <sub>OUT</sub> = 2.0V		7		4	pF	

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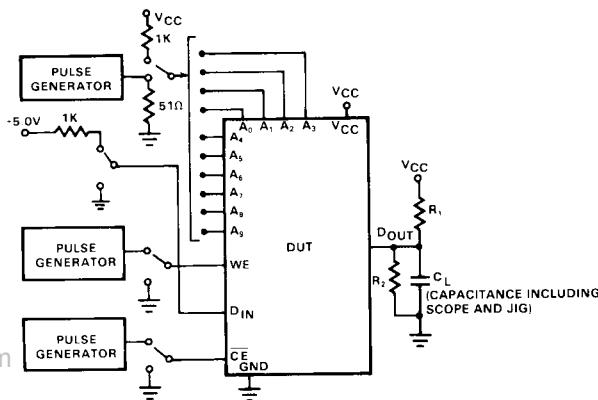
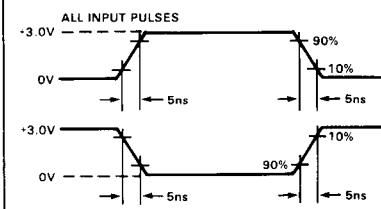
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**AC ELECTRICAL CHARACTERISTICS<sup>2</sup>** $R_1 = 270\Omega, R_2 = 600\Omega, C_L = 30pF$ N82S10/110/11/111:  $0^\circ C \leq T_A \leq +75^\circ C, 4.75V \leq V_{CC} \leq 5.25V$ S82S10/11:  $-55^\circ C \leq T_A \leq +125^\circ C, 4.5V \leq V_{CC} \leq 5.5V$ 

PARAMETER	TO	FROM	N82S10/11			N82S110/111			S82S10/11			UNIT
			Min	Typ <sup>3</sup>	Max	Min	Typ	Max	Min	Typ <sup>3</sup>	Max	
Access time TAA Address TCE Chip enable				30 15	40 30				30 25		30 15	60 45 ns
Disable time TCD Twd	Output Output	Chip enable Write enable		15 20	30 30				25 20		15 20	45 ns
TWR Write recovery time				20	30				25		20	45 ns
Setup and hold time TWSA Setup time TWHA Hold time	Write enable	Address	5 5	0 0		5 5			15 10	0 0		ns
TWSD Setup time TWHD Hold time	Write enable	Data in	30 5	25 0		25 5			55 5	35 0		
TWSC Setup time TWHC Hold time	Write enable	CE	5 5	0 0		5			5	0		
Pulse width TWP Write enable <sup>10</sup>				30	25		20		50	25		ns

## NOTES

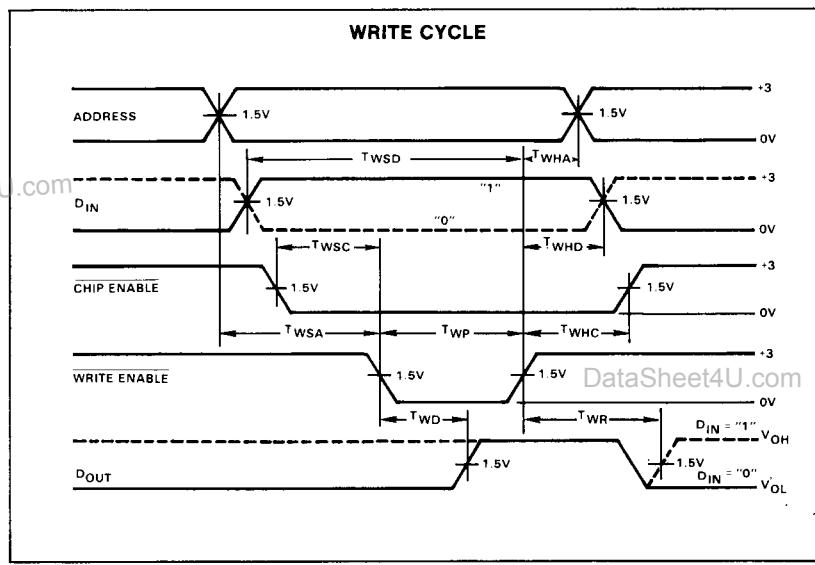
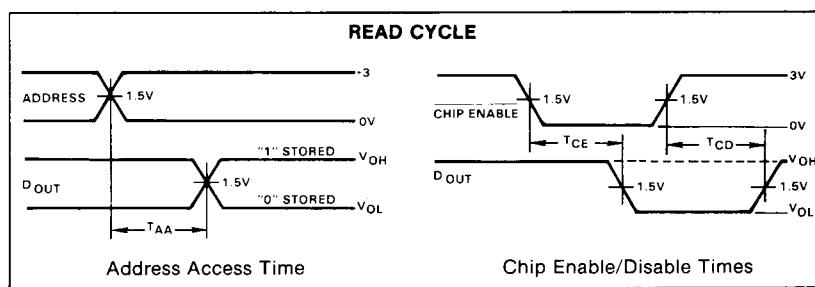
- All voltage values are with respect to network ground terminal.
- The operating ambient temperature ranges are guaranteed with transverse air flow exceeding 400 linear feet per minute and a 2-minute warm-up.
- Typical thermal resistance values of the package at maximum temperature are:  
 $\theta_{JA}$  junction to ambient at 400fpm air flow -  $50^\circ C/watt$   
 $\theta_{JA}$  junction to ambient - still air -  $90^\circ C/watt$   
 $\theta_{JA}$  junction to case -  $20^\circ C/watt$
- All typical values are at  $V_{CC} = 5V, T_A = 25^\circ C$ .
- Test each input one at a time.
- Measured with a logic low stored. Output sink current is supplied through a resistor to  $V_{CC}$ .
- Measured with  $V_{IL}$  applied to CE and a logic high stored.
- Measured with  $V_{IH}$  applied to CE.
- Duration of the short circuit should not exceed 1 second.
- Icc is measured with the write enable and memory enable inputs grounded, all other inputs at 4.5V, and the output open.
- Minimum required to guarantee a Write into the slowest bit.

**TEST LOAD CIRCUIT****LOADING CONDITION****VOLTAGE WAVEFORM****INPUT PULSES**

Measurements: All circuit delays are measured at the  $+1.5V$  level of inputs and output.

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**TIMING DIAGRAMS****MEMORY TIMING DEFINITIONS**

TWR	Delay between end of Write Enable pulse and when Data Output becomes valid. (Assuming Address still valid—not as shown.)
TCE	Delay between beginning of Chip Enable low (with Address valid) and when Data Output becomes valid.
TCD	Delay between when Chip Enable becomes high and Data Output is in off state.
TAA	Delay between beginning of valid Address (with Chip Enable low) and when Data Output becomes valid.
Twsc	Required delay between beginning of valid Chip Enable and beginning of Write Enable pulse.
TWHD	Required delay between end of Write Enable pulse and end of valid Input Data.
TWP	Width of Write Enable pulse.
TWSA	Required delay between beginning of valid Address and beginning of Write Enable pulse.
TWSD	Required delay between beginning of valid Data Input and end of Write Enable pulse.
TWD	Delay between beginning of Write Enable pulse and when Data Output is in off state.
TWHC	Required delay between end of Write Enable pulse and end of Chip Enable.
TWHA	Required delay between end of Write Enable pulse and end of valid Address.

**BIPOLAR MEMORY**